

Title (en)

Method for cold rolling seamless copper pipes

Title (de)

Verfahren zum Kaltwalzen von nahtlosen Kupferrohren

Title (fr)

Procédé de laminage à froid de tubes en cuivre sans soudure

Publication

**EP 1232808 A3 20040929 (DE)**

Application

**EP 02000996 A 20020117**

Priority

DE 10107567 A 20010217

Abstract (en)

[origin: EP1232808A2] Production of seamless non-ferrous, especially copper tubes from a continuously cast or extruded round bar (3) uses a round forging machine with planetary drive. A cooled zone (K) is set up around the forming area (U) by concentrated spraying from all sides with coolant (15). The workpiece is maintained below its recrystallization temperature.

IPC 1-7

**B21B 45/02**; **B21B 19/06**

IPC 8 full level

**B21B 9/00** (2006.01); **B21B 19/06** (2006.01); **B21B 45/02** (2006.01); **B21B 3/00** (2006.01); **B21B 25/04** (2006.01)

CPC (source: EP KR US)

**B21B 19/06** (2013.01 - EP KR US); **B21B 45/0215** (2013.01 - EP US); **B21B 9/00** (2013.01 - EP US); **B21B 25/04** (2013.01 - EP US); **B21B 2003/005** (2013.01 - EP US); **B21B 2045/0227** (2013.01 - EP US)

Citation (search report)

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